

Serial No. 09/761,317

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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-26 (canceled)

Claim 27 (previously presented): A method of wiring formation comprising the steps of:

forming a feeder film partially on a substrate;

forming on the substrate a plating base film such that the plating base film partially overlaps the feeder film;

forming a plated wiring on the plating base film; and

selectively removing at least a portion of the feeder film that is exposed from the plated wiring such that the feeder film under the plating base film is completely removed.

Claim 28 (previously presented): A method of wiring formation according to Claim 27, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

Claim 29 (previously presented): A method of wiring formation according to Claim 27, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

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Claim 30 (previously presented): A method of wiring formation according to Claim 27, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

Claim 31 (previously presented): A method of wiring formation according to Claim 27, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 32 (previously presented): A method of wiring formation according to Claim 27, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.